

P-Channel Power MOSFET

-30V, -36A, 15mΩ

FEATURES

- Low $R_{DS(on)}$ to minimize conductive Loss
- Low gate charge for fast power switching
- 100% UIS tested
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

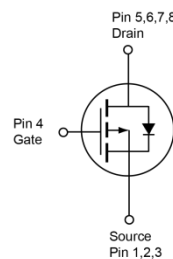
PRODUCT SUMMARY			
PARAMETER	VALUE	UNIT	
V_{DS}	-30	V	
$R_{DS(on)}$ (max)	$V_{GS} = -10V$	15	mΩ
	$V_{GS} = -4.5V$	30	
Q_g	14.3	nC	

APPLICATIONS

- DC-DC Converters
- Battery Power Management
- Oring FET/Load Switch



PDFN33



Note: MSL 1 (Moisture Sensitivity Level) per J-STD-020

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)			
PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current (Note 1)	I_D	$T_C = 25^\circ\text{C}$	-36
		$T_A = 25^\circ\text{C}$	-10
Pulsed Drain Current (Note 1)	I_{DM}	-144	A
Single Pulse Avalanche Current (Note 2)	I_{AS}	-31	A
Single Pulse Avalanche Energy (Note 2)	E_{AS}	48	mJ
Total Power Dissipation	P_D	$T_C = 25^\circ\text{C}$	27.8
		$T_C = 125^\circ\text{C}$	5.5
Total Power Dissipation	P_D	$T_A = 25^\circ\text{C}$	2.3
		$T_A = 125^\circ\text{C}$	0.5
Operating Junction and Storage Temperature Range	T_J, T_{STG}	- 55 to +150	$^\circ\text{C}$

THERMAL RESISTANCE			
PARAMETER	SYMBOL	LIMIT	UNIT
Thermal Resistance – Junction to Case	$R_{\theta JC}$	4.5	$^\circ\text{C/W}$
Thermal Resistance – Junction to Ambient	$R_{\theta JA}$	53	$^\circ\text{C/W}$

Notes: $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistances. The case-thermal reference is defined at the solder mounting surface of the drain pins. $R_{\theta JA}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Static (Note 3)						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = -250\mu A$	BV_{DSS}	-30	--	--	V
Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = -250\mu A$	$V_{GS(TH)}$	-1.2	-1.6	-2.5	V
Gate-Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$	I_{GSS}	--	--	± 100	nA
Drain-Source Leakage Current	$V_{GS} = 0V, V_{DS} = -30V$	I_{DSS}	--	--	-1	μA
Drain-Source On-State Resistance	$V_{GS} = -10V, I_D = -10A$	$R_{DS(on)}$	--	13	15	m Ω
	$V_{GS} = -4.5V, I_D = -10A$		--	22	30	
Forward Transconductance	$V_{DS} = -5V, I_D = -10A$	g_{fs}	--	19	--	S
Dynamic (Note 4)						
Total Gate Charge	$V_{GS} = -10V, V_{DS} = -15V, I_D = -10A$	Q_g	--	29.3	--	nC
Total Gate Charge	$V_{GS} = -4.5V, V_{DS} = -15V, I_D = -10A$	Q_g	--	14.3	--	
Gate-Source Charge		Q_{gs}	--	5.9	--	
Gate-Drain Charge		Q_{gd}	--	5.2	--	
Input Capacitance	$V_{GS} = 0V, V_{DS} = -15V, f = 1.0\text{MHz}$	C_{iss}	--	1829	--	pF
Output Capacitance		C_{oss}	--	227	--	
Reverse Transfer Capacitance		C_{rss}	--	160	--	
Switching (Note 4)						
Turn-On Delay Time	$V_{GS} = -10V, V_{DS} = -15V, I_D = -1A, R_G = 6\Omega,$	$t_{d(on)}$	--	9	--	ns
Rise Time		t_r	--	21.8	--	
Turn-Off Delay Time		$t_{d(off)}$	--	59.8	--	
Fall Time		t_f	--	14.4	--	
Source-Drain Diode (Note 3)						
Diode Forward Voltage	$V_{GS} = 0V, I_S = -10A$	V_{SD}	--	--	-1	V
Reverse Recovery Time	$I_S = -10A, di/dt = 100A/\mu s$	t_{rr}	--	34	--	ns
Reverse Recovery Charge		Q_{rr}	--	23	--	nC

Notes:

1. Current limited by package.
2. $L = 0.1\text{mH}, V_{GS} = -10V, V_{DS} = -25V, R_G = 25\Omega, I_{AS} = -31A$, Starting $T_J = 25^\circ\text{C}$
3. Pulse test: Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
4. Switching time is essentially independent of operating temperature.

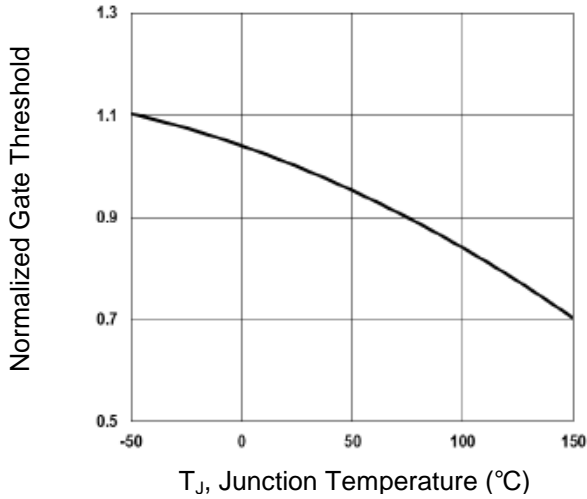
ORDERING INFORMATION

PART NO.	PACKAGE	PACKING
TSM150P03PQ33 RGG	PDFN33	5,000pcs / 13" Reel

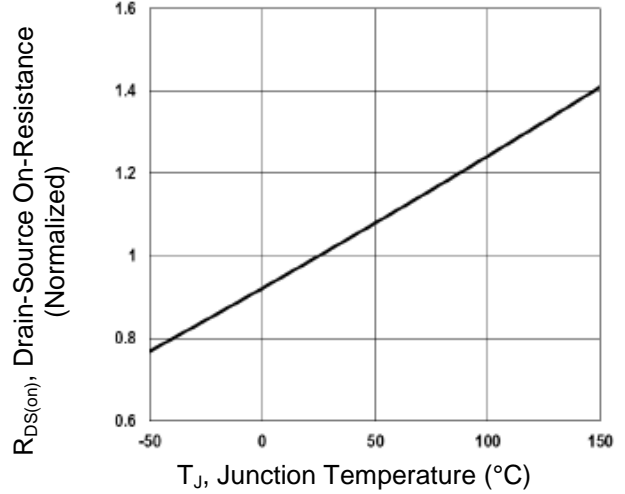
CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

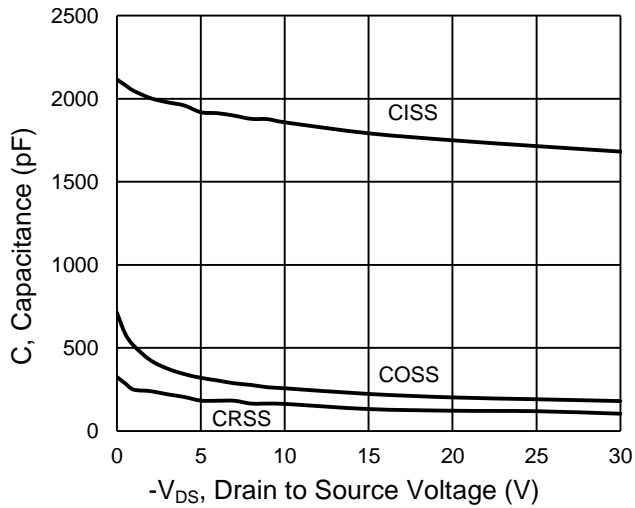
Normalized V_{th} vs. T_J



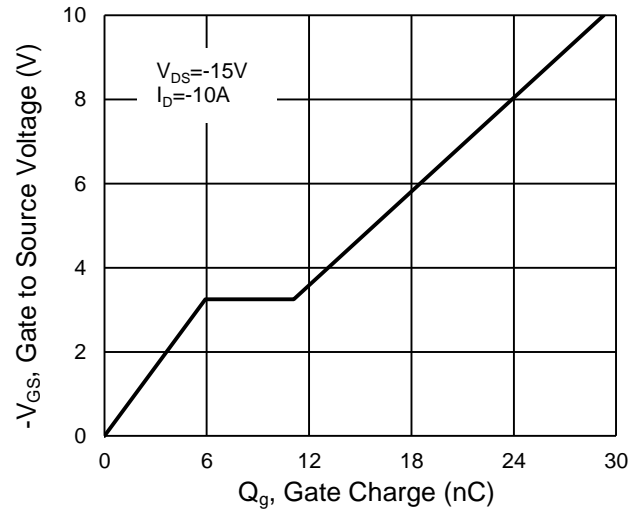
On-Resistance vs. Junction Temperature



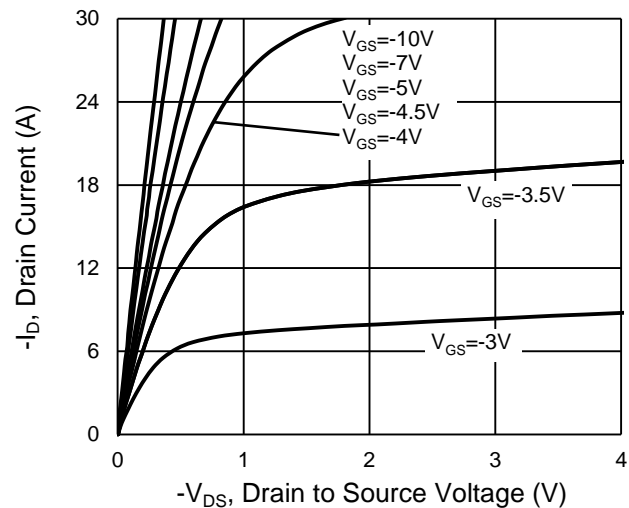
Capacitance vs. Drain-Source Voltage



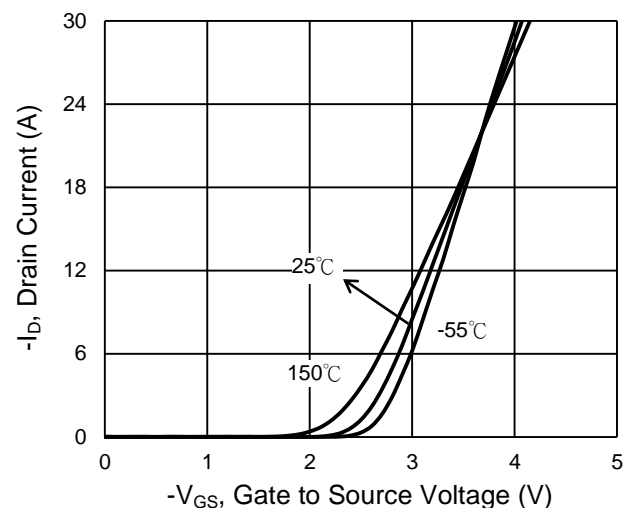
Gate-Source Voltage vs. Gate Charge



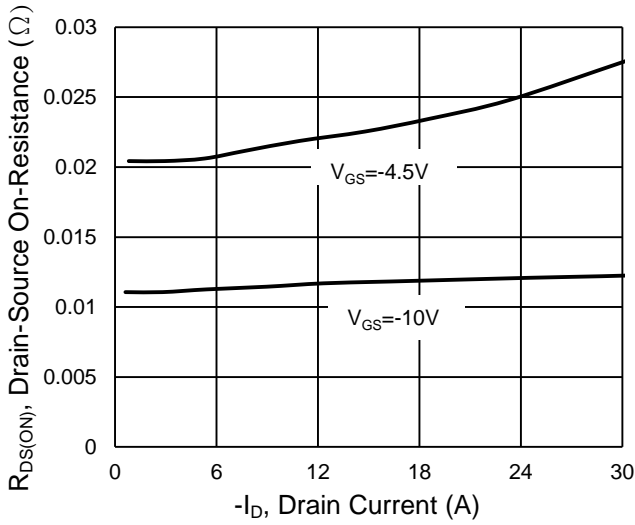
Output Characteristics



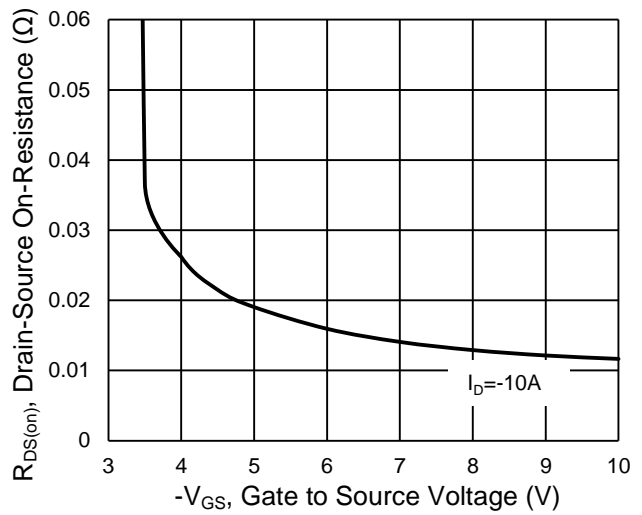
Transfer Characteristics



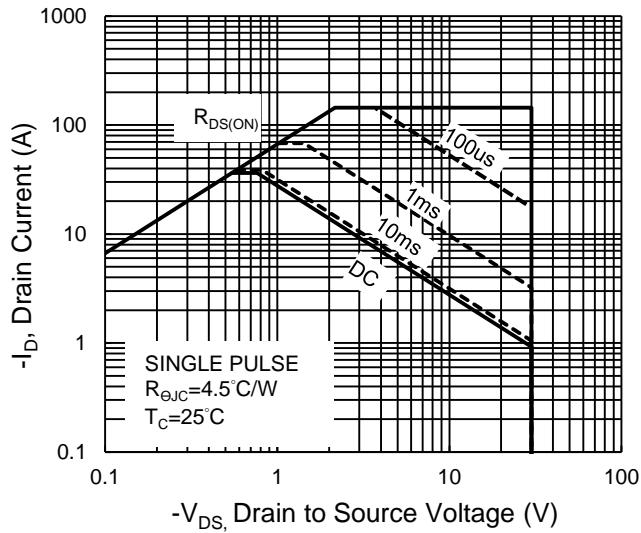
On-Resistance vs. Drain Current



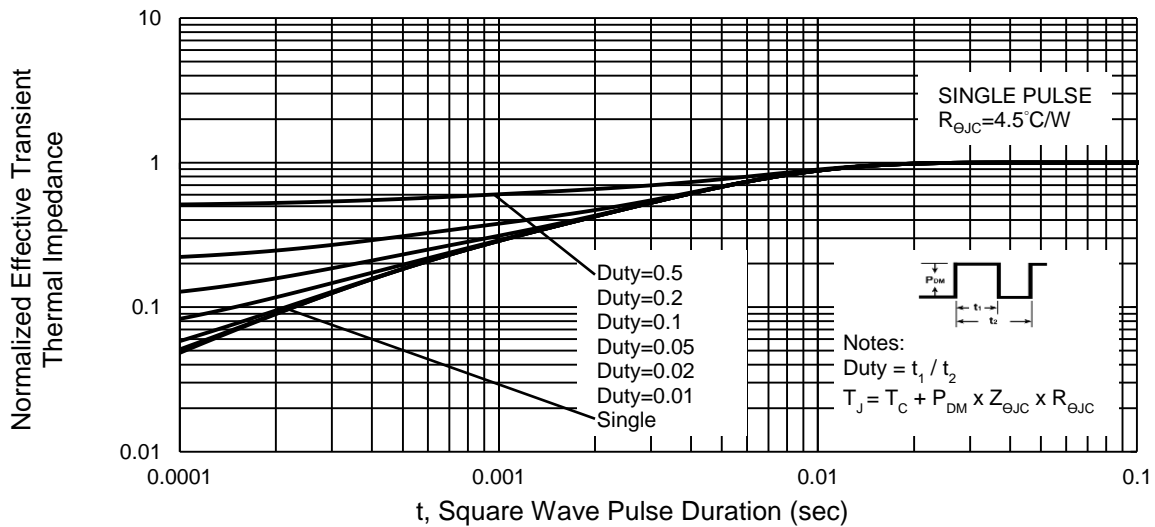
On-Resistance vs. Gate-Source Voltage



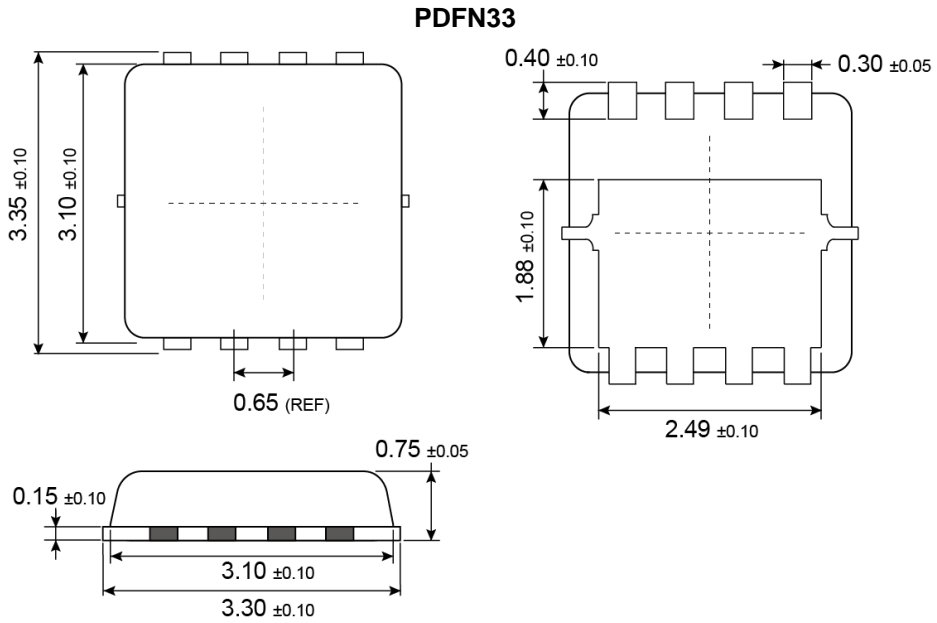
Maximum Safe Operating Area, Junction-to-Case



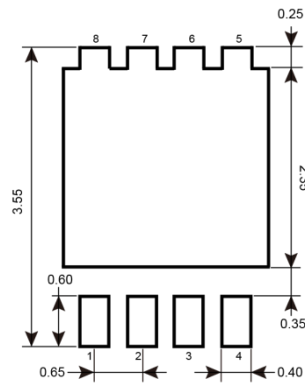
Normalized Thermal Transient Impedance, Junction-to-Case



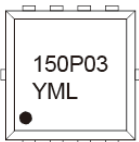
PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)



SUGGESTED PAD LAYOUT (Unit: Millimeters)



MARKING DIAGRAM



- Y** = Year Code
- M** = Month Code for Halogen Free Product
 - O** =Jan **P** =Feb **Q** =Mar **R** =Apr
 - S** =May **T** =Jun **U** =Jul **V** =Aug
 - W** =Sep **X** =Oct **Y** =Nov **Z** =Dec
- L** = Lot Code (1~9, A~Z)

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